

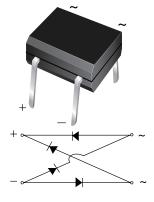
MB2M, MB4M & MB6M

RoHS

COMPLIANT

Vishay General Semiconductor

Miniature Glass Passivated Single-Phase Bridge Rectifiers



Case Style MBM

| PRIMARY CHARACTERISTICS | | | | | |
|-------------------------|---------------------|--|--|--|--|
| I _{F(AV)} | 0.5 A | | | | |
| V _{RRM} | 200 V, 400 V, 600 V | | | | |
| I _{FSM} | 35 A | | | | |
| I _R | 5 μΑ | | | | |
| V _F | 1.0 V | | | | |
| Т _Ј max. | 150 °C | | | | |

FEATURES

- UL recognition, file number E54214
- · Ideal for printed circuit boards
- Applicable for automative insertion
- High surge current capability
- · Recommended for non-automotive applications
- Solder dip 260 °C, 40 s
- Component in accordance to RoHS 2002/95/EC and WEEE 2002/96/EC

TYPICAL APPLICATIONS

General purpose use in ac-to-dc bridge full wave rectification for power supply, lighting ballaster, battery charger, home appliances, office equipment, and telecommunication applications.

MECHANICAL DATA

Case: MBM

Epoxy meets UL 94V-0 flammability rating

Terminals: Matte tin plated leads, solderable per J-STD-002 and JESD22-B102

E3 suffix for consumer grade, meets JESD 201 class 1A whisker test

Polarity: As marked on body

| MAXIMUM RATINGS (T _A = 25 °C unless otherwise noted) | | | | | | |
|---|-----------------------------------|--|------|------|------------------|--|
| PARAMETER | SYMBOL | MB2M | MB4M | MB6M | UNIT | |
| Device marking code | | 2 | 4 | 6 | | |
| Maximum repetitive peak reverse voltage | V _{RRM} | 200 | 400 | 600 | V | |
| Maximum RMS voltage | V _{RMS} | 140 | 280 | 420 | V | |
| Maximum DC blocking voltage | V _{DC} | 200 | 400 | 600 | V | |
| Maximum average forward output on glass-epoxy P.C.B. on aluminum substrate | I _{F(AV)} | 0.5 ⁽¹⁾ 0.8 ⁽²⁾ | | | А | |
| Peak forward surge current 8.3 ms single half sine-wave superimposed on rated load | I _{FSM} | 35 | | | A | |
| Rating for fusing (t < 8.3 ms) | l ² t | 5.0 | | | A ² s | |
| Operating junction and storage temperature range | T _J , T _{STG} | - 55 to + 150 | | | °C | |

Notes:

(1) On glass epoxy P.C.B. mounted on 0.05 x 0.05" (1.3 x 1.3 mm) pads

(2) On aluminum substrate P.C.B. with an area of 0.8" x 0.8" (20 x 20 mm) mounted on 0.05 x 0.05" (1.3 x 1.3 mm) solder pad

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| ELECTRICAL CHARACTERISTICS ($T_A = 25 \degree C$ unless otherwise noted) | | | | | | | |
|--|---|----------------|------------|------|------|------|--|
| PARAMETER | TEST CONDITIONS | SYMBOL | MB2M | MB4M | MB6M | UNIT | |
| Maximum instantaneous forward voltage drop per diode | 0.4 A | V _F | 1.0 | | | V | |
| Maximum DC reverse current at rated DC blocking voltage per diode | T _A = 25 °C T _A = 125 °C | I _R | 5.0 100 | | μA | | |
| Typical junction capacitance per diode $^{(1)}$ | | CJ | | 13 | | pF | |

Note:

(1) Measured at 1.0 MHz and applied reverse voltage of 4.0 V

| THERMAL CHARACTERISTICS ($T_A = 25 \text{ °C}$ unless otherwise noted) | | | | | | |
|--|--|---|------|------|------|--|
| PARAMETER | SYMBOL | MB2M | MB4M | MB6M | UNIT | |
| Typical thermal resistance | ${f R}_{	heta JA} \ {f R}_{	heta JA} \ {f R}_{	heta JL}$ | 85 ⁽¹⁾ 70 ⁽²⁾ 20 ⁽¹⁾ | | | °C/W | |

Notes:

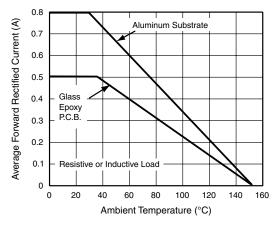
(1) On glass epoxy P.C.B. mounted on 0.05 x 0.05" (1.3 x 1.3 mm) pads

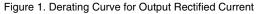
(2) On aluminum substrate P.C.B. with an area of 0.8" x 0.8" (20 x 20 mm) mounted on 0.05 x 0.05" (1.3 x 1.3 mm) solder pad

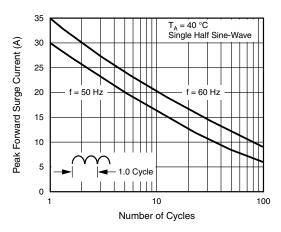
| ORDERING INFORMATION (Example) | | | | | | |
|--------------------------------|-----------------|------------------------|---------------|---------------|--|--|
| PREFERRED P/N | UNIT WEIGHT (g) | PREFERRED PACKAGE CODE | BASE QUANTITY | DELIVERY MODE | | |
| MB2M-E3/45 | 0.22 | 45 | 100 | Tube | | |

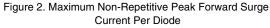
RATINGS AND CHARACTERISTICS CURVES

(T_A = 25 °C unless otherwise noted)









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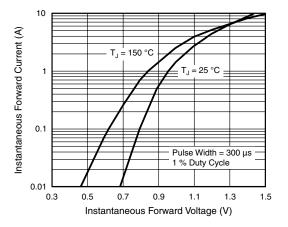


Figure 3. Typical Forward Voltage Characteristics Per Diode

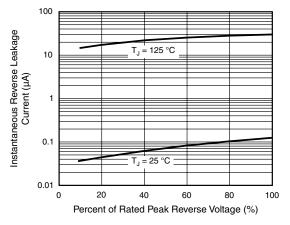
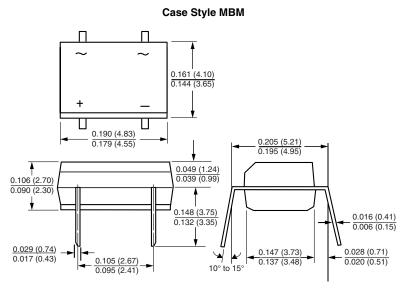


Figure 4. Typical Reverse Leakage Characteristics Per Diode

PACKAGE OUTLINE DIMENSIONS in inches (millimeters)



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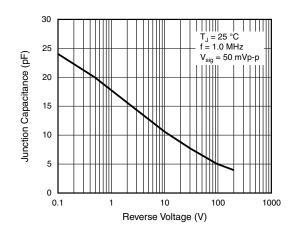


Figure 5. Typical Junction Capacitance Per Diode



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